

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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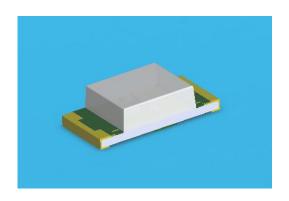




GHT

DATASHEET

SMD B B EAST16084BA8



Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Description

- The SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Ver.: 1 Rel ease Date: 06/01/2017

狀態: Devel oping(開發階段)



Device Selection Guide

Chip Materials	Emitted Color	Resin Color	
InGaN	Blue	Water Clear	

Absolute Maximum Ratings (Ta=25°C)

Parameter Parameter	Symbol	Rating	Unit
Reverse Voltage	V_{R}	5	V
Forward Current	l _F	10	mA
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA
Power Dissipation	Pd	40	mW
Electrostatic Discharge	ESD _{HBM}	150	V
Operating Temperature	T_{opr}	-40 ~ +85	$^{\circ}$
Storage Temperature	Tstg	-40 ~ +100	$^{\circ}\! \mathbb{C}$
Soldering Temperature	Tsol	Reflow Soldering : 260 $^\circ\!$	



Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	18.0		45.0	mcd	_
Viewing Angle	2 θ _{1/2}		120		deg	
Peak Wavelength	λр		468		nm	_
Dominant Wavelength	λd	465.0		475.0	nm	[—] I _F =5mA
Spectrum Radiation Bandwidth	Δλ		25		nm	
Forward Voltage	V _F	2.60		3.00	V	
Reverse Current	I _R			50	μΑ	V _R =5V
Note: 1.Tolerance of Luminous Intensity: ±11% 2.Tolerance of Dominant Wavelength ±1nm 3. Tolerance of Forward Voltage: ±0.05V						

Note:

- 1.Tolerance of Luminous Intensity: ±11%
- 2. Tolerance of Dominant Wavelength ±1nm
- 3. Tolerance of Forward Voltage: ±0.05V



Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
M1	18.0	22.5		
M2	22.5	28.5		J. 5 A
N1	28.5	36.0	mcd	$I_F = 5mA$
N2	36.0	45.0		

Bin Range Of Dom. Wavelength

Bin Code	Min.	Max.	Unit	Condition
X	465.0	470.0		Ι
Υ	470.0	475.0	─ nm	I _F =5mA

Bin Range Of Forward Voltage

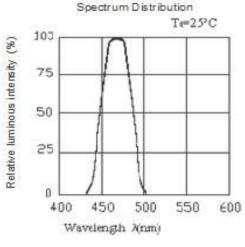
Bin Code	Min.	Max.	Unit	Condition
28	2.60	2.70		
29	2.70	2.80	V	I _F =5mA
30	2.80	2.90	v	IF =SIIIA
31	2.90	3.00		

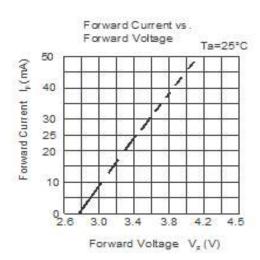
Note:

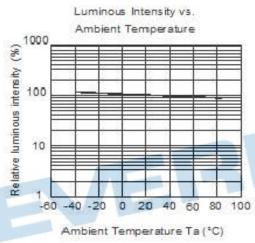
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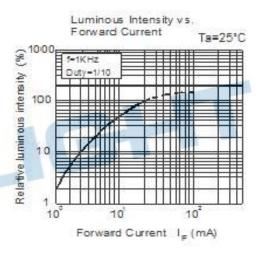


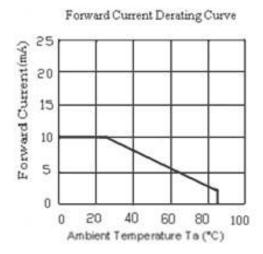
Typical Electro-Optical Characteristics Curves

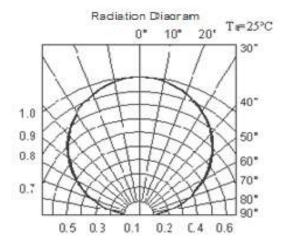






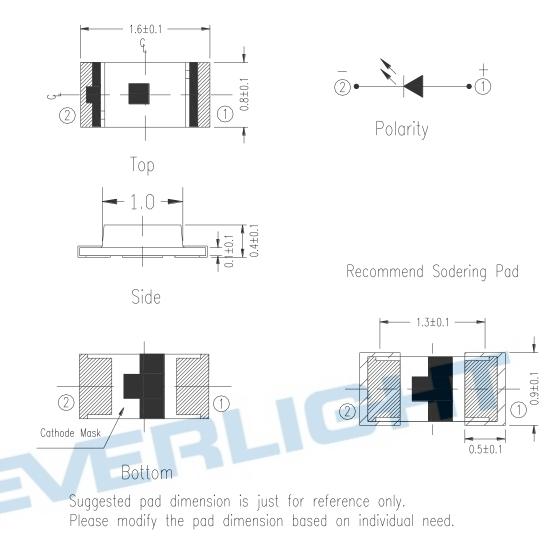








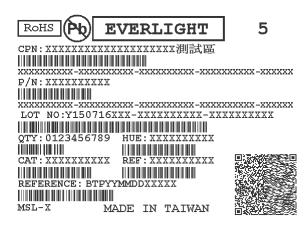
Package Dimension



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

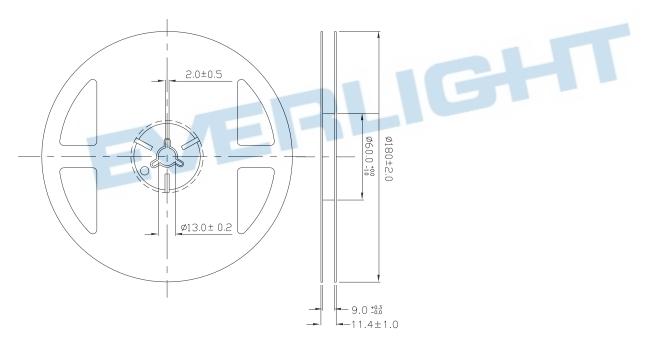


Moisture Resistant Packing Materials Label Explanation



- · CPN: Customer's Product Number
- P/N: Product Number
- · QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- · LOT No: Lot Number

Reel Dimensions

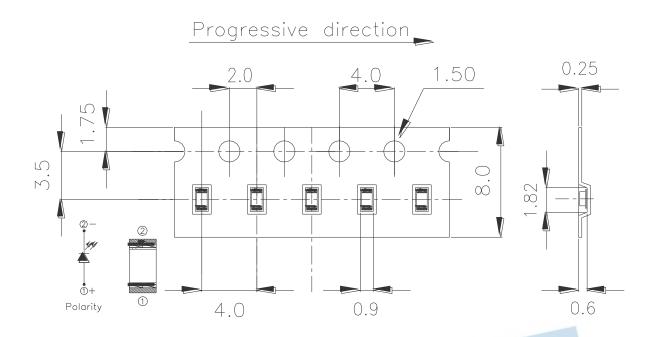


Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

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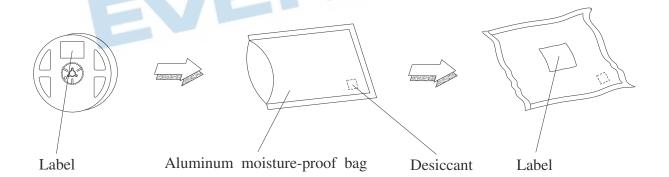


Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Moisture Resistant Packaging





Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

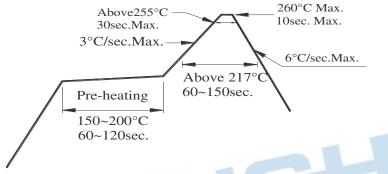
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30° C or less and 60% RH or less.

If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



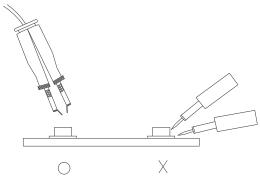
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlightamericas before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.



Ver.: 1 Rel ease Date: 06/01/2017 狀態: Devel opi ng(開發階段)



DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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- 6. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.



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